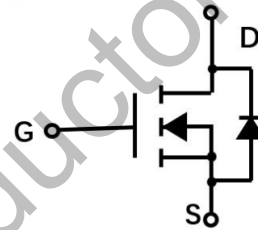


#### Features

- 100V, 50A
- $R_{DS(ON)} = 18m\Omega$  (Max.) @  $V_{GS} = 10V, I_D = 20A$
- Low  $R_{DS(on)}$  & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- 100% UIS tested , 100%  $\Delta V_{DS}$  Tested
- RoHS and Halogen-Free Compliant

#### Application

- High Frequency Switching
- Synchronous Rectification



#### Absolute Maximum Ratings $T_C=25^\circ C$ unless otherwise specified

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		100	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current <sup>note5</sup>	$T_C = 25^\circ C$	50	A
$I_D$	Continuous Drain Current <sup>note5</sup>	$T_C = 100^\circ C$	31.5	A
$I_{DM}$	Pulsed Drain Current <sup>note3</sup>		200	A
$P_D$	Power Dissipation <sup>note2</sup>	$T_C = 25^\circ C$	68	W
$I_{AS}$	Avalanche Current <sup>note3,6</sup>		21	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>note3,6</sup>		110	mJ
$R_{\theta JC}$	Thermal Resistance, Junction to Case		1.85	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>note1,4</sup>		55	$^\circ C/W$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ C$

\*Drain current limited by maximum junction temperature

**Electrical Characteristics**  $T_C=25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	100	-	-	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS} = 80V, V_{GS} = 0V$	-	-	1	$\mu A$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.2	1.8	2.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 20A$	-	15	18	mΩ
		$V_{GS} = 4.5V, I_D = 10A$	-	19.5	25	mΩ
$R_g$	Gate Resistance	$V_{DS} = V_{GS}=0V, f = 1.0MHz$	-	1.49	-	Ω
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = 50V, V_{GS} = 0V,$ $f = 1.0MHz$	-	1004	-	pF
$C_{oss}$	Output Capacitance		-	186	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	6.5	-	pF
<b>Switching Characteristics</b>						
$Q_g$	Total Gate Charge	$V_{DS} = 50V, I_D = 40A,$ $V_{GS} = 10V$	-	26.1	-	nC
$Q_{gs}$	Gate-Source Charge		-	8.0	-	
$Q_{gd}$	Gate-Drain("Miller") Charge		-	3.3	-	
$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = 50V, I_D = 20A,$ $R_G = 3\Omega, V_{GS}=10V$	-	5.4	-	ns
$t_r$	Turn-On Rise Time		-	2.9	-	
$t_{d(off)}$	Turn-Off Delay Time		-	10.8	-	
$t_f$	Turn-Off Fall Time		-	2.1	-	
<b>Diode Characteristics</b>						
$I_S$	Continuous Source Current		-	-	50	A
$V_{SD}$	Diode Forward Voltage	$I_S=20A, V_{GS} = 0V$	-	0.88	1.0	V
$t_{rr}$	Reverse Recovery Time	$I_{SD}=20A,$	-	34	-	ns
$Q_{rr}$	Reverse Recovery Charge	$dI_{SD}/dt=100A/\mu s$	-	35	-	nC

**Notes:**

- The value of  $R_{\theta JC}$  is measured in a still air environment with  $T_A = 25^\circ\text{C}$  and the maximum allowed junction temperature of  $150^\circ\text{C}$ . The value in any given application depends on the user's specific board design.
- The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
- Single pulse width limited by junction temperature  $T_{J(MAX)}=150^\circ\text{C}$ .
- The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to case  $R_{\theta JC}$  and case to ambient.
- The maximum current rating is package limited.
- The EAS data shows Max. rating. The test condition is  $V_{DS}=50V, V_{GS}=10V, L=0.5mH$

### Typical Performance Characteristics

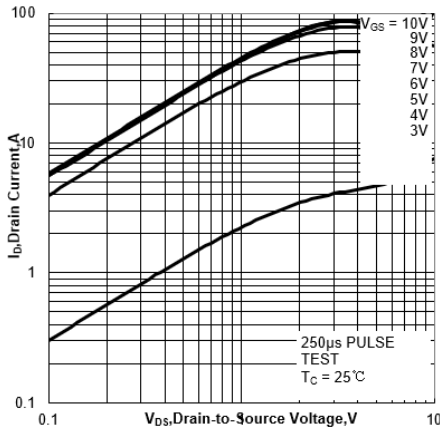


Figure 1. Output Characteristics

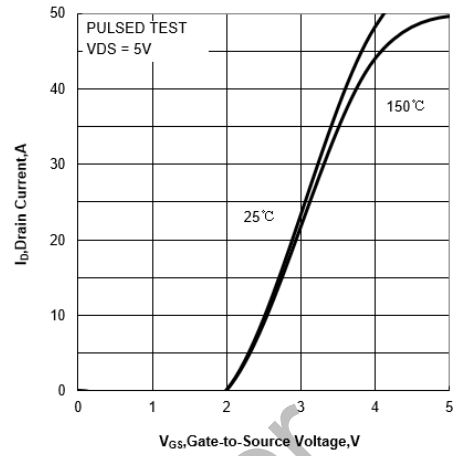


Figure 2. Transfer Characteristics

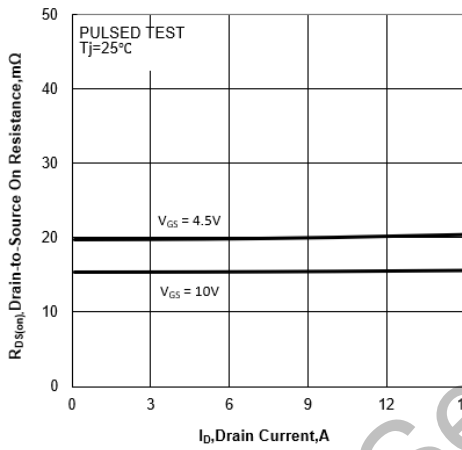


Figure 3. Drain-to-Source On Resistance vs Drain Current

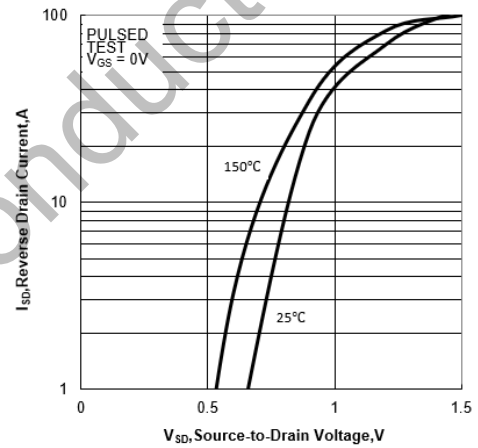


Figure 4. Body Diode Forward Voltage vs Source Current and Temperature

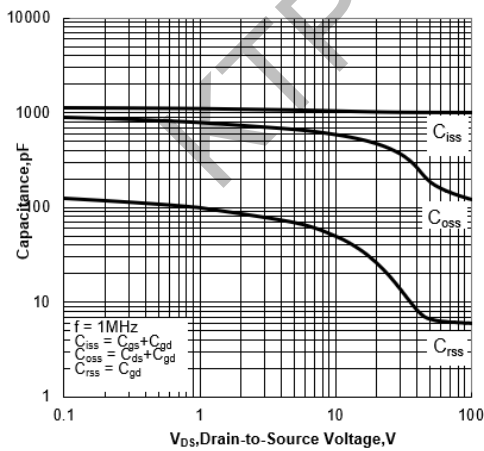


Figure 5. Capacitance Characteristics

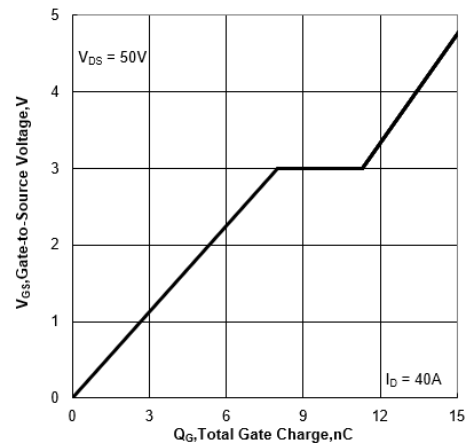
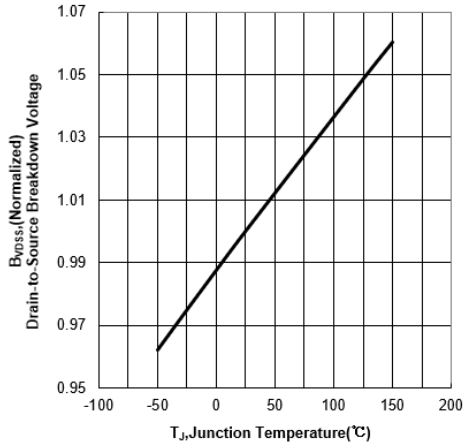
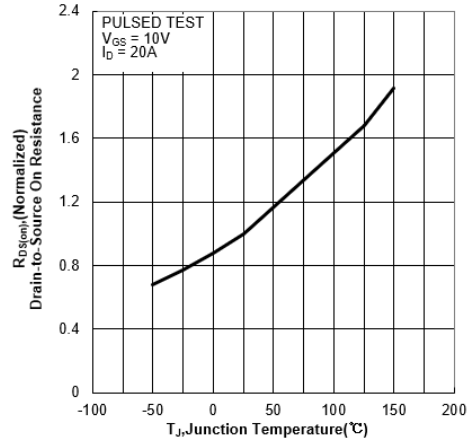


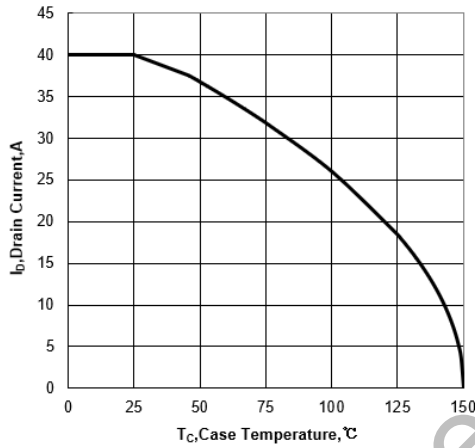
Figure 6. Gate Charge Characteristics



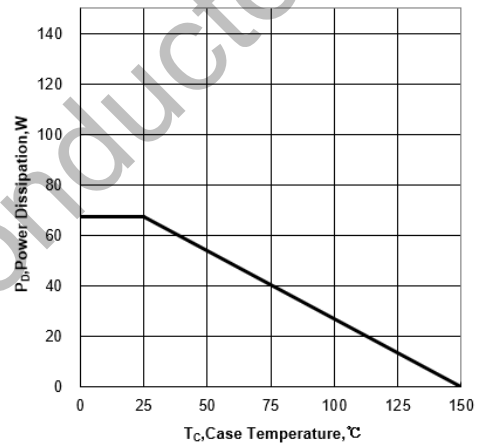
**Figure 7. Normalized Breakdown Voltage vs Junction Temperature**



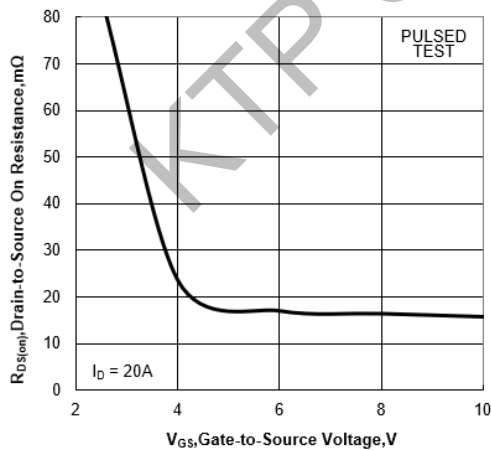
**Figure 8. Normalized On Resistance vs Junction Temperature**



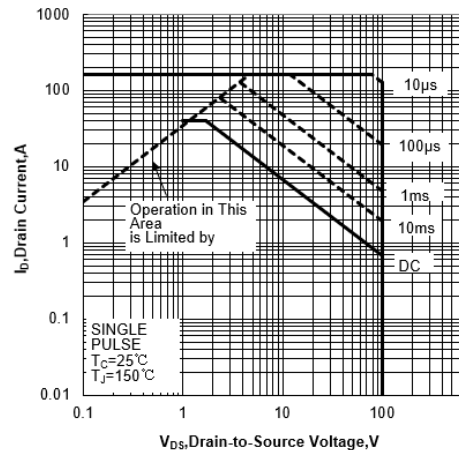
**Figure 9. Maximum Continuous Drain Current vs Case Temperature**



**Figure 10. Maximum Power Dissipation vs Case Temperature**



**Figure 11. Drain-to-Source On Resistance vs Gate Voltage and Drain Current**



**Figure 12. Maximum Safe Operating Area**

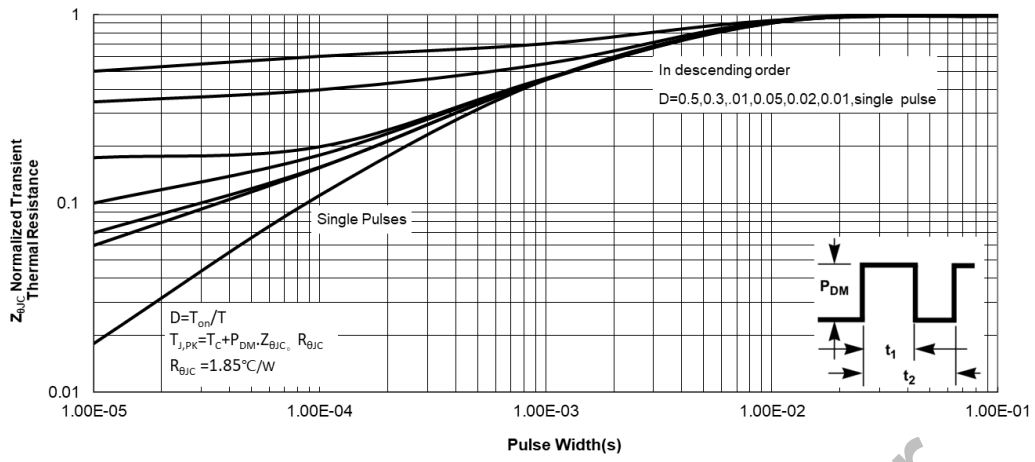
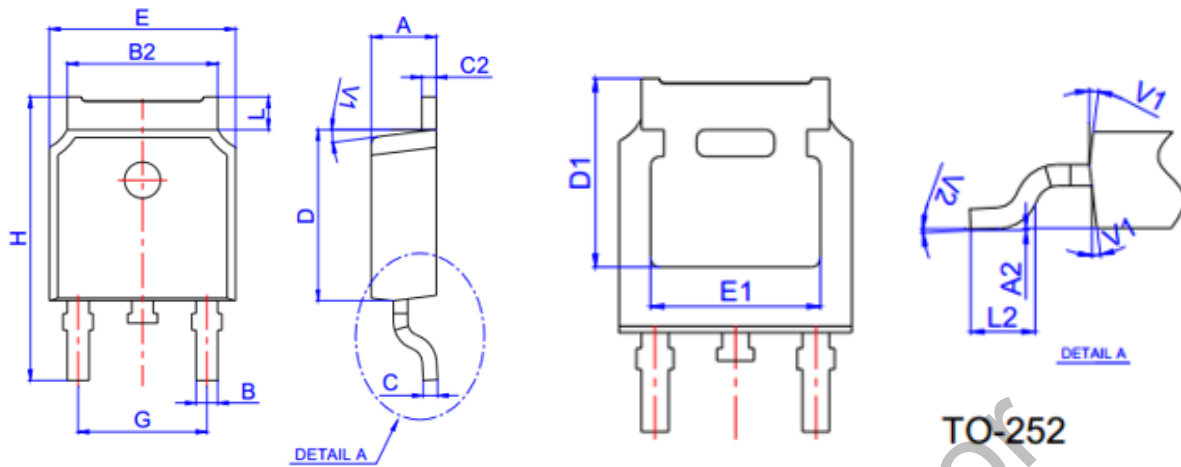


Figure 13. Maximum Effective Transient Thermal Impedance, Junction-to-Case

KTP Semiconductor

### TO-252-3L Package Mechanical Data



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°